

Epoxy Based Interconnect Solutions

Technology

Cinch has engineered a hermetic epoxy potting process that passes rigorous helium leakage requirements. This process is adaptable to many connector styles and can also be applied to feed through headers. These interconnects function reliably under extreme environmental conditions such as, high pressure, temperature and exposure to propellants.

Key Advantages of Epoxy Solution

- Cost savings - 50-70% less cost than traditional fired glass or ceramic solutions
- Weight reduction
- Reduced lead-time
- Less tooling

Common Applications

- GPS systems
- Inertial Navigation Systems
- Gyroscopes
- Other high reliability military and commercial applications



Performance Characteristics

Helium Leak Rate	Up to 1×10^{-9} cc/sec
Thermal Shock	-65°C to +125°C, over 500 cycles
Dielectric Withstanding Voltage	500 VAC RMS at sea level
Insulation Resistance	>100 megohms @ 100 Volts DC



Cinch Connectivity Solutions
1700 Finley Road
Lombard, IL 60148 USA

+1 630.705.6000
inquiry@cinch.com
cinch.com